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ON Semiconductor®

FDS8949-F085

Dual N-Channel Logic Level PowerTrench[®] MOSFET 40V, 6A, 29m Ω

Features

- Max r_{DS(on)} = 29mΩ at V_{GS} = 10V
- Max r_{DS(on)} = 36mΩ at V_{GS} = 4.5V
- Low gate charge
- High performance trench technology for extremely low ^rDS(on)
- High power and current handling capability
- Qualified to AEC Q101
- RoHS compliant



General Description

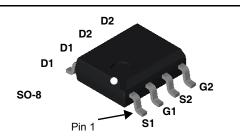
These N-Channel Logic Level MOSFETs are produced using ON Semiconductor's advanced PowerTrench[®] process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

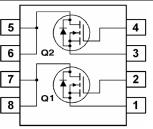
These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.

Applications

Inverter

Power suppliers





MOSFET Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DS}	Drain to Source Voltage		40	V
V _{GS}	Gate to Source Voltage		±20	V
	Drain Current -Continuous	(Note 1a)	6	A
D	-Pulsed		20	A
E _{AS}	Drain-Source Avalanche Energy	(Note 3)	26	mJ
P _D	Power Dissipation for Dual Operation 2			
	Power Dissipation for Single Operation	(Note 1a)	1.6	W
		(Note 1b)	0.9	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to 150	°C
Thermal	Characteristics			
$R_{\theta JA}$	Thermal Resistance-Single operation, Junction to Ambient	(Note 1a)	81	
R _{θJA}	Thermal Resistance-Single operation, Junction to Ambient	(Note 1b)	135	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	40	

Package Marking and Ordering Information

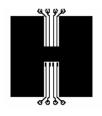
Device Marking	Device	Reel Size	Tape Width	Quantity
FDS8949	FDS8949-F085	13"	12mm	2500 units

1

Symbol	Parameter	Test Conditions	Min	Тур	Мах	Units
Off Char	acteristics					
3V _{DSS}	Drain to Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	40			V
ΔBV _{DSS} ΔT _J	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, referenced to 25°C		33		mV/°C
DSS	Zero Gate Voltage Drain Current	$V_{DS} = 32V, V_{GS} = 0V$ $T_J = 55^{\circ}C$			1 10	μA μA
GSS	Gate to Source Leakage Current	$T_{J} = 55^{\circ}C$ $V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA
	acteristics (Note 2)					
	Gate to Source Threshold Voltage	V _{GS} = V _{DS} , I _D = 250μA	1	1.9	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_{.l}}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu A$, referenced to 25°C		-4.6	0	mV/°C
0	Drain to Source On Resistance	V _{GS} = 10V, I _D = 6A		21	29	mΩ
r _{DS(on)}		V _{GS} = 4.5V, I _D = 4.5A		26	36	
		V _{GS} = 10V, I _D = 6A,T _J = 125°C		29	43	
					70	
J _{FS}	Forward Transconductance	$V_{DS} = 10V, I_D = 6A$		22		S
)ynamic C _{iss}	Characteristics	$V_{DS} = 10V, I_D = 6A$ $V_{DS} = 20V, V_{GS} = 0V,$		22 715	955	pF
Dynamic C _{iss} C _{oss}	Characteristics Input Capacitance Output Capacitance	V _{DS} = 10V,I _D = 6A		22 715 105	955 140	pF pF
Dynamic C _{iss} C _{oss} C _{rss}	Characteristics	$V_{DS} = 10V, I_D = 6A$ $V_{DS} = 20V, V_{GS} = 0V,$		22 715	955	pF
Dynamic C _{iss} C _{oss} C _{rss} R _g Switchin	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance g Characteristics	$V_{DS} = 10V, I_D = 6A$ $V_{DS} = 20V, V_{GS} = 0V,$ f = 1MHz		22 715 105 60 1.1	955 140 90	pF pF pF Ω
Dynamic C _{iss} C _{oss} C _{rss} Rg Switchin	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance g Characteristics Turn-On Delay Time	$V_{DS} = 10V, I_D = 6A$ $V_{DS} = 20V, V_{GS} = 0V,$ f = 1MHz f = 1MHz		22 715 105 60 1.1	955 140 90 18	pF pF pF Ω
Dynamic C _{iss} C _{oss} C _{rss} Rg Switchin d(on) r	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance g Characteristics Turn-On Delay Time Rise Time	$V_{DS} = 10V, I_D = 6A$ $V_{DS} = 20V, V_{GS} = 0V,$ f = 1MHz		22 715 105 60 1.1 9 5	955 140 90 18 10	pF pF pF Ω ns
Dynamic Ciss Coss Crss Crss Crss Crss Crss Crss Cr	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance g Characteristics Turn-On Delay Time Rise Time Turn-Off Delay Time	$V_{DS} = 10V, I_D = 6A$ $V_{DS} = 20V, V_{GS} = 0V,$ f = 1MHz f = 1MHz $V_{DD} = 20V, I_D = 1A$		22 715 105 60 1.1 9 5 23	955 140 90 18 10 37	pF pF pF Ω ns ns
Dynamic C _{iss} C _{oss} C _{rss} Rg Switchin d(on) r d(off) f	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance g Characteristics Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time	$V_{DS} = 10V, I_D = 6A$ $V_{DS} = 20V, V_{GS} = 0V,$ f = 1MHz f = 1MHz $V_{DD} = 20V, I_D = 1A$		22 715 105 60 1.1 9 5 23 3	955 140 90 18 10 37 6	pF pF Ω ns ns ns ns
Dynamic \sum_{iss} \sum_{crss} rss Switchin d(on) r d(off) f λ_g	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance g Characteristics Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time Total Gate Charge	$V_{DS} = 10V, I_D = 6A$ $V_{DS} = 20V, V_{GS} = 0V,$ $f = 1MHz$ $f = 1MHz$ $V_{DD} = 20V, I_D = 1A$ $V_{GS} = 10V, R_{GEN} = 6\Omega$		22 715 105 60 1.1 9 5 23 3 7.7	955 140 90 18 10 37	pF pF Ω ns ns ns ns ns
Dynamic \sum_{iss} \sum_{css} R_g Switchin $\frac{d(on)}{r}$ d(off) f Q_g Q_{gs}	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance Characteristics Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time Total Gate Charge Gate to Source Gate Charge	$V_{DS} = 10V, I_D = 6A$ $V_{DS} = 20V, V_{GS} = 0V,$ f = 1MHz f = 1MHz $V_{DD} = 20V, I_D = 1A$		22 715 105 60 1.1 9 5 23 3 7.7 2.4	955 140 90 18 10 37 6	pF pF pF Ω ns ns ns ns nc nC
Dynamic \sum_{iss} \sum_{crss} rss Switchin d(on) r d(off) f λ_g	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance g Characteristics Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time Total Gate Charge	$V_{DS} = 10V, I_D = 6A$ $V_{DS} = 20V, V_{GS} = 0V,$ $f = 1MHz$ $f = 1MHz$ $V_{DD} = 20V, I_D = 1A$ $V_{GS} = 10V, R_{GEN} = 6\Omega$		22 715 105 60 1.1 9 5 23 3 7.7	955 140 90 18 10 37 6	pF pF Ω ns ns ns ns ns
Dynamic \sum_{iss} \sum_{rss} R_g Switchin d(off) f A_g A_g A_g A_g A_g A_g	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance Characteristics Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time Total Gate Charge Gate to Source Gate Charge	$V_{DS} = 10V, I_D = 6A$ $V_{DS} = 20V, V_{GS} = 0V,$ f = 1MHz f = 1MHz $V_{DD} = 20V, I_D = 1A$ $V_{GS} = 10V, R_{GEN} = 6\Omega$ $V_{DS} = 20V, I_D = 6A, V_{GS} = 5V$		22 715 105 60 1.1 9 5 23 3 7.7 2.4	955 140 90 18 10 37 6	pF pF pF Ω ns ns ns ns nc nC
Dynamic C_{iss} C_{rss} C_{rss} Switchin d(on) r d(off) f Q_g Q_{gs} Q_{gd} Drain-So	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance g Characteristics Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time Total Gate Charge Gate to Source Gate Charge Gate to Drain "Miller"Charge	$V_{DS} = 10V, I_D = 6A$ $V_{DS} = 20V, V_{GS} = 0V,$ $f = 1MHz$ $f = 1MHz$ $V_{DD} = 20V, I_D = 1A$ $V_{GS} = 10V, R_{GEN} = 6\Omega$ $V_{DS} = 20V, I_D = 6A, V_{GS} = 5V$ and Maximum Ratings		22 715 105 60 1.1 9 5 23 3 7.7 2.4	955 140 90 18 10 37 6	pF pF pF Ω ns ns ns ns nc nC
Dynamic \sum_{iss} \sum_{rss} R_g Switchin d(off) f A_g A_g A_g A_g A_g A_g	Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance Gate Resistance Characteristics Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time Total Gate Charge Gate to Source Gate Charge Gate to Drain "Miller"Charge Characteristics a	$V_{DS} = 10V, I_D = 6A$ $V_{DS} = 20V, V_{GS} = 0V,$ $f = 1MHz$ $f = 1MHz$ $V_{DD} = 20V, I_D = 1A$ $V_{GS} = 10V, R_{GEN} = 6\Omega$ $V_{DS} = 20V, I_D = 6A, V_{GS} = 5V$ and Maximum Ratings		22 715 105 60 1.1 9 5 23 3 7.7 2.4 2.8	955 140 90 18 10 37 6 11	pF pF Ω ns ns ns nC nC

Notes:

1: R_{0JA} is the sum of the junction-to-case and case-to- ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0JC} is guaranteed by design while R_{0JA} is determined by the user's board design.



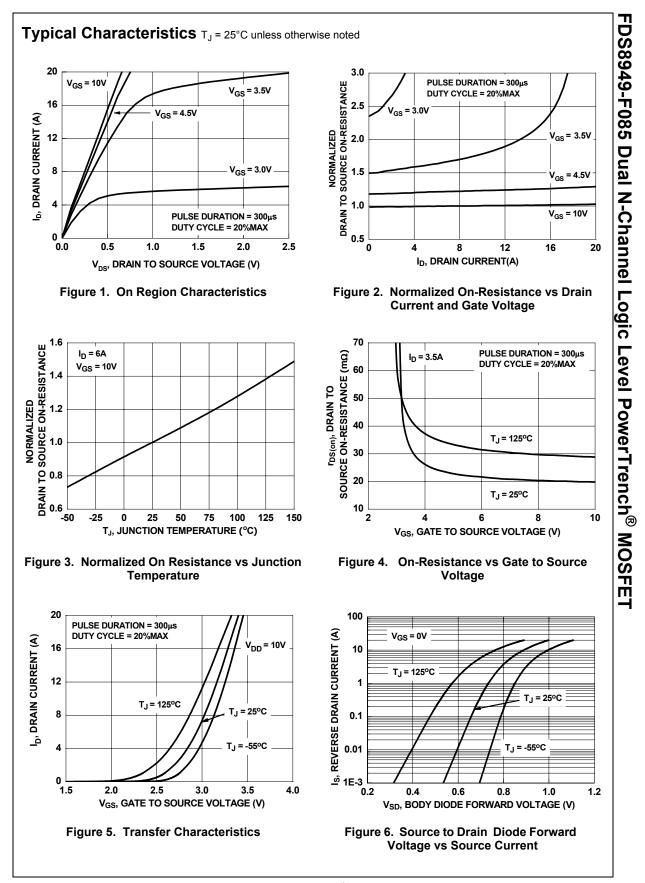
 $\label{eq:2.1} \begin{array}{l} \textbf{2:} \mbox{Pulse Test: Pulse Width < 300 us, Duty Cycle < 2.0\%.} \\ \textbf{3:} \mbox{Starting T}_J = 25^\circ\mbox{C}, \mbox{L} = 1\mbox{mH}, \mbox{I}_{AS} = 7.3\mbox{A}, \mbox{V}_{DD} = 40\mbox{V}, \mbox{V}_{GS} = 10\mbox{V}. \end{array}$

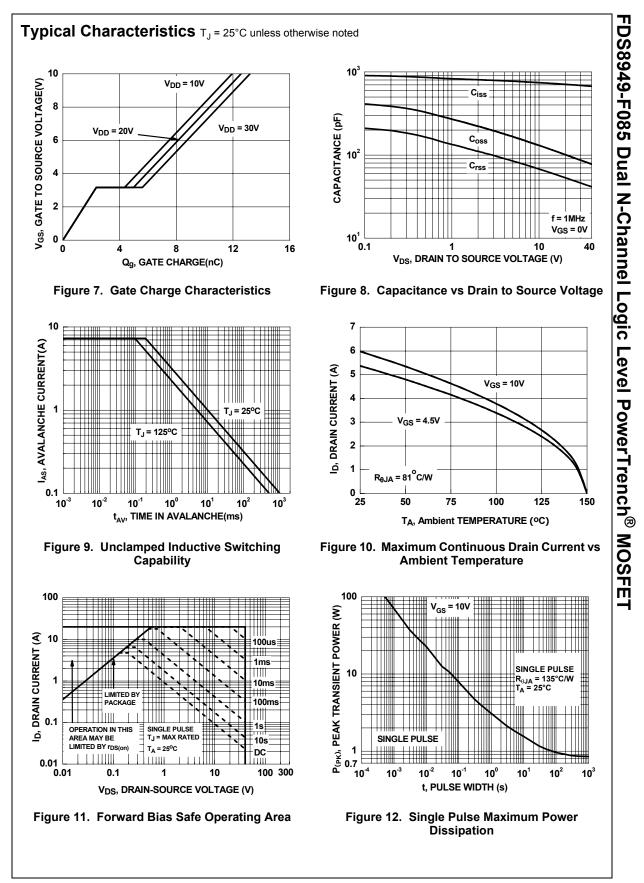
a) 81°C/W when mounted on a 1in² pad of 2 oz copper

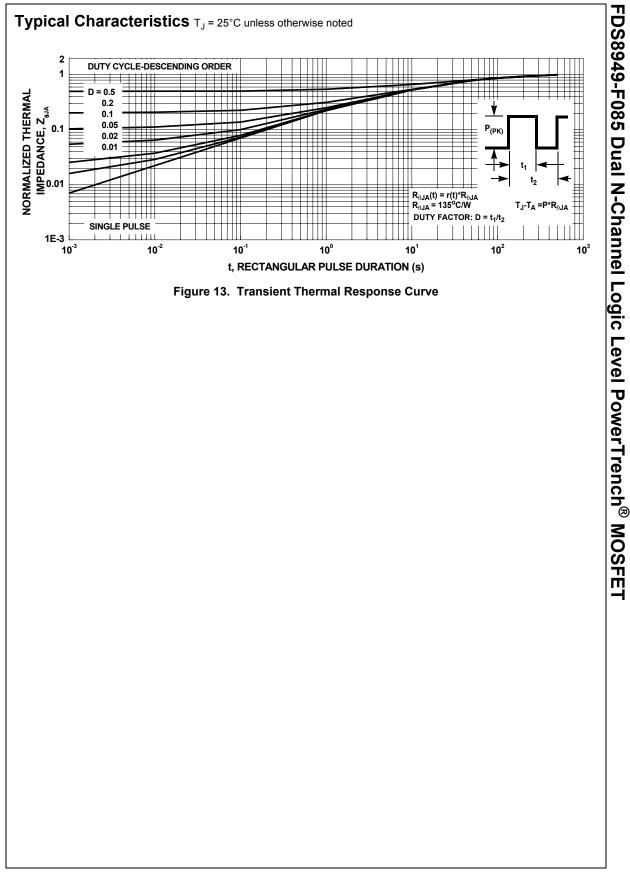
Scale 1:1 on letter size paper

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**b)** 135°C/W when mounted on a minimum pad .







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